- **Low Power Consumption**
- **Wide Common-Mode and Differential Voltage Ranges**
- **Low Input Bias and Offset Currents**
- **Output Short-Circuit Protection**
- **Low Total Harmonic Distortion . . . 0.003% Typ**
- **High Input Impedance . . . JFET-Input Stage**
- **Latch-Up-Free Operation**
- **High Slew Rate . . . 13 V/μs Typ**
- **Common-Mode Input Voltage Range Includes V_{CC+}**

description/ordering information

The TL08x JFET-input operational amplifier family is designed to offer a wider selection than any previously developed operational amplifier family. Each of these JFET-input operational amplifiers incorporates well-matched, high-voltage JFET and bipolar transistors in a monolithic integrated circuit. The devices feature high slew rates, low input bias and offset currents, and low offset-voltage temperature coefficient. Offset adjustment and external compensation options are available within the TL08x family.

The C-suffix devices are characterized for operation from 0°C to 70°C. The I-suffix devices are characterized for operation from −40°C to 85°C. The Q-suffix devices are characterized for operation from −40°C to 125°C. The M-suffix devices are characterized for operation over the full military temperature range of −55°C to 125°C.

ORDERING INFORMATION

T_J	V_{IO}max AT 25°C	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	15 mV	PDIP (P)	Tube of 50	TL081CP	TL081CP
			Tube of 50	TL082CP	TL082CP
		PDIP (N)	Tube of 25	TL084CN	TL084CN
		SOIC (D)	Tube of 75	TL081CD	TL081C
			Reel of 2500	TL081CDR	
			Tube of 75	TL082CD	TL082C
			Reel of 2500	TL082CDR	
			Tube of 50	TL084CD	TL084C
			Reel of 2500	TL084CDR	
		SOP (PS)	Reel of 2000	TL081CPSR	T081
			Reel of 2000	TL082CPSR	T082
		SOP (NS)	Reel of 2000	TL084CNSR	TL084
		TSSOP (PW)	Tube of 150	TL082CPW	T082
			Reel of 2000	TL082CPWR	
			Tube of 90	TL084CPW	T084
			Reel of 2000	TL084CPWR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

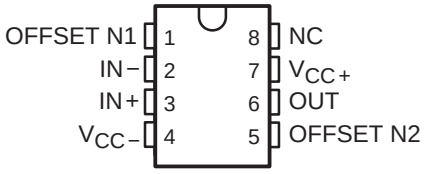
description/ordering information (continued)

ORDERING INFORMATION

T_J	V_{IO}max AT 25°C	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	6 mV	PDIP (P)	Tube of 50	TL081ACP	TL081ACP
			Tube of 50	TL082ACP	TL082ACP
		PDIP (N)	Tube of 25	TL084ACN	TL084ACN
		SOIC (D)	Tube of 75	TL081ACD	081AC
			Reel of 2500	TL081ACDR	
			Tube of 75	TL082ACD	082AC
			Reel of 2500	TL082ACDR	
			Tube of 50	TL084ACD	TL084AC
			Reel of 2500	TL084ACDR	
		SOP (PS)	Reel of 2000	TL082ACPSR	T082A
		SOP (NS)	Reel of 2000	TL084ACNSR	TL084A
	3 mV	PDIP (P)	Tube of 50	TL081BCP	TL081BCP
			Tube of 50	TL082BCP	TL082BCP
		PDIP (N)	Tube of 25	TL084BCN	TL084BCN
		SOIC (D)	Tube of 75	TL081BCD	081BC
			Reel of 2500	TL081BCDR	
			Tube of 75	TL082BCD	082BC
			Reel of 2500	TL082BCDR	
			Tube of 50	TL084BCD	TL084BC
			Reel of 2500	TL084BCDR	
−40°C to 85°C	6 mV	PDIP (P)	Tube of 50	TL081IP	TL081IP
			Tube of 50	TL082IP	TL082IP
		PDIP (N)	Tube of 25	TL084IN	TL081IN
		SOIC (D)	Tube of 75	TL081ID	TL081I
			Reel of 2500	TL081IDR	
			Tube of 75	TL082ID	TL082I
			Reel of 2500	TL082IDR	
			Tube of 50	TL084ID	TL084I
			Reel of 2500	TL084IDR	
		TSSOP (PW)	Reel of 2000	TL082IPWR	Z082
−40°C to 125°C	9 mV	SOIC (D)	Tube of 50	TL084QD	TL084QD
			Reel of 2500	TL084QDR	
−55°C to 125°C	9 mV	CDIP (J)	Tube of 25	TL084MJ	TL084MJ
		LCCC (FK)	Reel of 55	TL084FK	TL084FK
	6 mV	CDIP (JG)	Tube of 50	TL082MJG	TL082MJG
		LCCC (FK)	Tube of 55	TL082MFK	TL082MFK

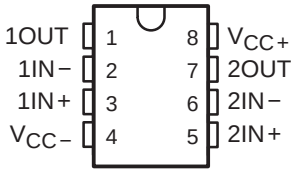
† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

TL081, TL081A, TL081B
D, P, OR PS PACKAGE
(TOP VIEW)

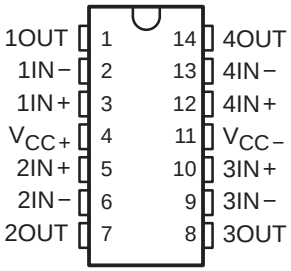


NC − No internal connection

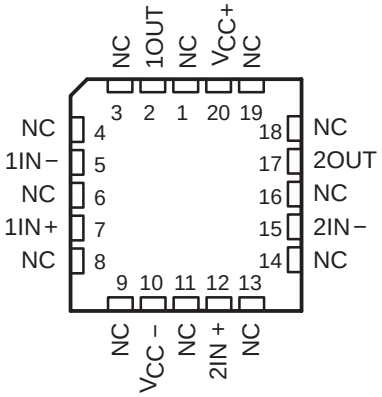
TL082, TL082A, TL082B
D, JG, P, PS, OR PW PACKAGE
(TOP VIEW)



TL084, TL084A, TL084B
D, J, N, NS, OR PW PACKAGE
(TOP VIEW)

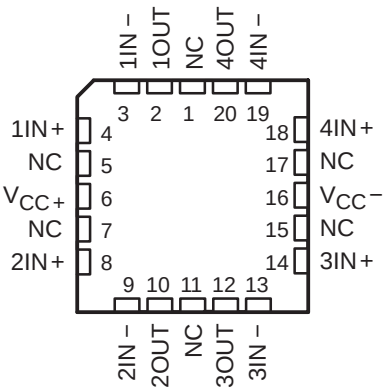


TL082M . . . FK PACKAGE
(TOP VIEW)



NC − No internal connection

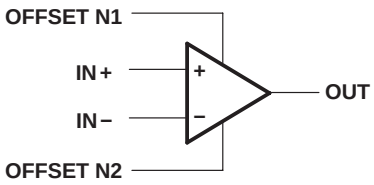
TL084M . . . FK PACKAGE
(TOP VIEW)



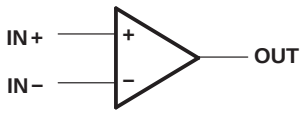
NC − No internal connection

symbols

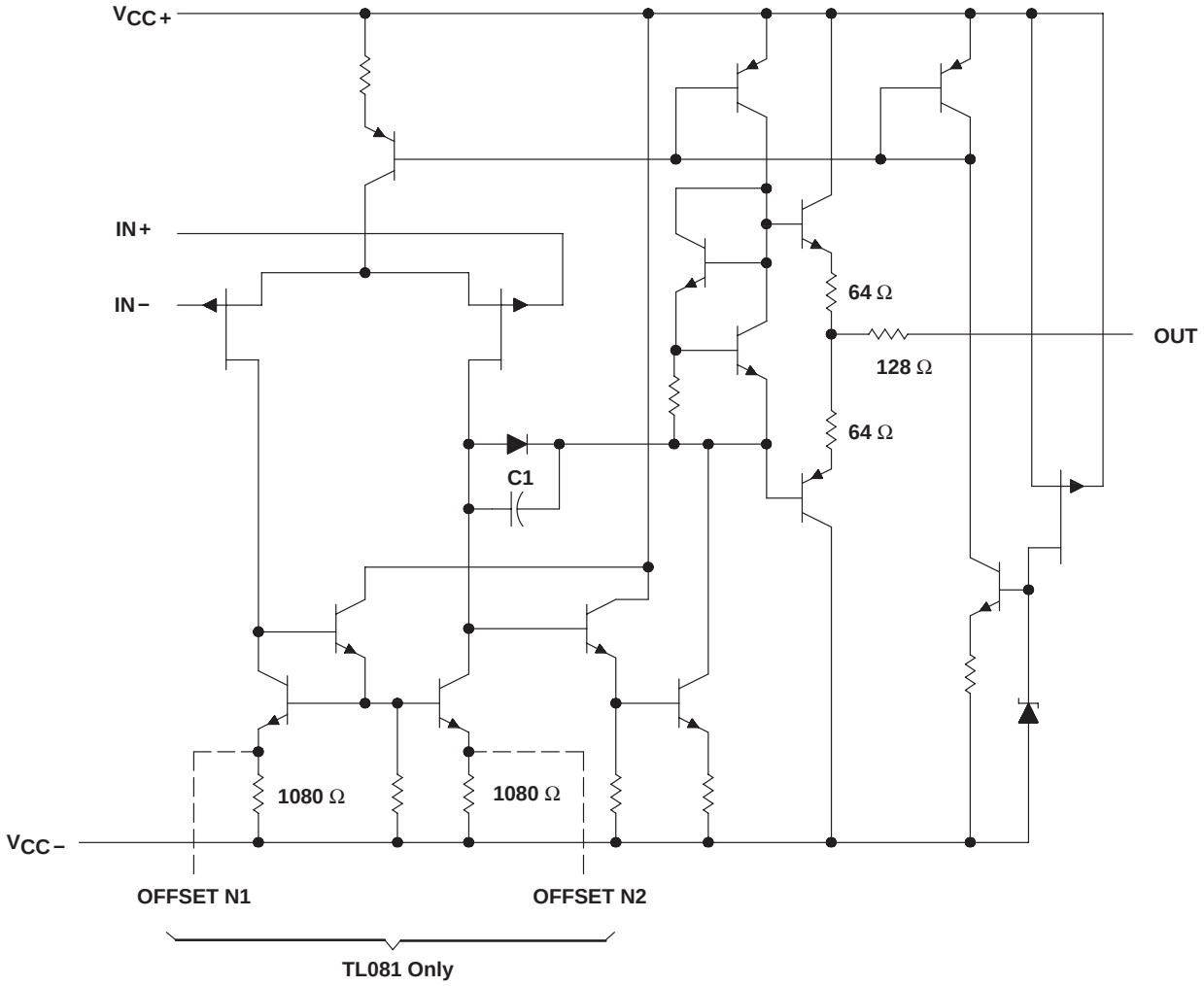
TL081



TL082 (EACH AMPLIFIER)
TL084 (EACH AMPLIFIER)



schematic (each amplifier)



Component values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

		TL08_C TL08_AC TL08_BC	TL08_I	TL084Q	TL08_M	UNIT
Supply voltage, V_{CC+} (see Note 1)		18	18	18	18	V
Supply voltage V_{CC-} (see Note 1)		−18	−18	−18	−18	V
Differential input voltage, V_{ID} (see Note 2)		±30	±30	±30	±30	V
Input voltage, V_I (see Notes 1 and 3)		±15	±15	±15	±15	V
Duration of output short circuit (see Note 4)		Unlimited	Unlimited	Unlimited	Unlimited	
Continuous total power dissipation		See Dissipation Rating Table				
Operating free-air temperature range, T_A		0 to 70	− 40 to 85	− 40 to 125	− 55 to 125	°C
Package thermal impedance, θ_{JA} (see Notes 5 and 6)	D package (8-pin)	97	97			°C/W
	D package (14-pin)	86	86			
	N package (14-pin)	76	76			
	NS package (14-pin)	80				
	P package (8-pin)	85	85			
	PS package (8-pin)	95	95			
	PW package (8-pin)	149				
	PW package (14-pin)	113	113			
Operating virtual junction temperature		150	150	150	150	°C
Case temperature for 60 seconds, T_C	FK package				260	°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds	J or JG package				300	°C
Storage temperature range, T_{stg}		− 65 to 150	− 65 to 150	− 65 to 150	− 65 to 150	°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES:
1. All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC-}.
2. Differential voltages are at IN+ with respect to IN−.
3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
4. The output may be shorted to ground or to either supply. Temperature and/or supply voltages must be limited to ensure that the dissipation rating is not exceeded.
5. Maximum power dissipation is a function of $T_J(max)$, θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
6. The package thermal impedance is calculated in accordance with JESD 51-7.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$ POWER RATING	DERATING FACTOR	DERATE ABOVE T_A	$T_A = 70°C$ POWER RATING	$T_A = 85°C$ POWER RATING	$T_A = 125°C$ POWER RATING
D (14 pin)	680 mW	7.6 mW/°C	60°C	604 mW	490 mW	186 mW
FK	680 mW	11.0 mW/°C	88°C	680 mW	680 mW	273 mW
J	680 mW	11.0 mW/°C	88°C	680 mW	680 mW	273 mW
JG	680 mW	8.4 mW/°C	69°C	672 mW	546 mW	210 mW

electrical characteristics, $V_{CC\pm}$ = ±15 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A†	TL081C, TL082C, TL084C			TL081AC, TL082AC, TL084AC			TLO81BC, TL082BC, TL084BC			TL081I, TL082I, TL084I			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO}	Input offset voltage	V_O = 0	R_S = 50 Ω	25°C		3	15		3	6		2	3		3	6	mV
				Full range			20			7.5			5			9	
α_{VIO}	Temperature coefficient of input offset voltage	V_O = 0	R_S = 50 Ω	Full range		18			18			18			18		µV/°C
I_{IO}	Input offset current‡	V_O = 0		25°C		5	200		5	100		5	100		5	100	pA
				Full range			2			2			2			10	nA
I_{IB}	Input bias current‡	V_O = 0		25°C		30	400		30	200		30	200		30	200	pA
				Full range			10			7			7			20	nA
V_{ICR}	Common-mode input voltage range			25°C	±11	−12 to 15		±11	−12 to 15		±11	−12 to 15		±11	−12 to 15		V
V_{OM}	Maximum peak output voltage swing	R_L = 10 kΩ		25°C	±12	±13.5		±12	±13.5		±12	±13.5		±12	±13.5		V
		R_L ≥ 10 kΩ		Full range	±12			±12			±12			±12			
		R_L ≥ 2 kΩ			±10	±12		±10	±12		±10	±12		±10	±12		
A_{VD}	Large-signal differential voltage amplification	V_O = ±10 V,	R_L ≥ 2 kΩ	25°C	25	200		50	200		50	200		50	200		V/mV
		V_O = ±10 V,	R_L ≥ 2 kΩ	Full range	15			25			25			25			
B_1	Unity-gain bandwidth			25°C		3			3			3			3		MHz
r_i	Input resistance			25°C		10^{12}			10^{12}			10^{12}			10^{12}		Ω
CMRR	Common-mode rejection ratio	V_{IC} = V_{ICR}min, V_O = 0,	R_S = 50 Ω	25°C	70	86		75	86		75	86		75	86		dB
k_{SVR}	Supply-voltage rejection ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$)	V_{CC} = ±15 V to ± 9 V, V_O = 0,	R_S = 50 Ω	25°C	70	86		80	86		80	86		80	86		dB
I_{CC}	Supply current (per amplifier)	V_O = 0,	No load	25°C		1.4	2.8		1.4	2.8		1.4	2.8		1.4	2.8	mA
V_{O1}/V_{O2}	Crosstalk attenuation	A_{VD} = 100		25°C		120			120			120			120		dB

† All characteristics are measured under open-loop conditions with zero common-mode voltage, unless otherwise specified. Full range for T_A is 0°C to 70°C for TL08_C, TL08_AC, TL08_BC and –40°C to 85°C for TL08_I.

‡ Input bias currents of an FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 17. Pulse techniques must be used that maintain the junction temperature as close to the ambient temperature as possible.

electrical characteristics, $V_{CC\pm}$ = ±15 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	T_A	TL081M, TL082M			TL084Q, TL084M			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO}	Input offset voltage	V_O = 0, R_S = 50 Ω	25°C		3	6		3	9	mV
			Full range			9			15	
α_{VIO}	Temperature coefficient of input offset voltage	V_O = 0 R_S = 50 Ω	Full range		18			18		μV/°C
I_{IO}	Input offset current‡	V_O = 0	25°C		5	100		5	100	pA
			125°C			20			20	nA
I_{IB}	Input bias current‡	V_O = 0	25°C		30	200		30	200	pA
			125°C			50			50	nA
V_{ICR}	Common-mode input voltage range		25°C	±11	−12 to 15		±11	−12 to 15		V
V_{OM}	Maximum peak output voltage swing	R_L = 10 kΩ	25°C	±12	±13.5		±12	±13.5		V
		R_L ≥ 10 kΩ	Full range	±12			±12			
		R_L ≥ 2 kΩ		±10	±12		±10	±12		
A_{VD}	Large-signal differential voltage amplification	V_O = ±10 V, R_L ≥ 2 kΩ	25°C	25	200		25	200		V/mV
		V_O = ±10 V, R_L ≥ 2 kΩ	Full range	15			15			
B_1	Unity-gain bandwidth		25°C		3			3		MHz
r_i	Input resistance		25°C		10^{12}			10^{12}		Ω
CMRR	Common-mode rejection ratio	V_{IC} = V_{ICR}min, V_O = 0, R_S = 50 Ω	25°C	80	86		80	86		dB
k_{SVR}	Supply-voltage rejection ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$)	V_{CC} = ±15 V to ±9 V, V_O = 0, R_S = 50 Ω	25°C	80	86		80	86		dB
I_{CC}	Supply current (per amplifier)	V_O = 0, No load	25°C		1.4	2.8		1.4	2.8	mA
V_{O1}/V_{O2}	Crosstalk attenuation	A_{VD} = 100	25°C		120			120		dB

† All characteristics are measured under open-loop conditions, with zero common-mode input voltage, unless otherwise specified.
‡ Input bias currents of a FET-input operational amplifier are normal junction reverse currents, which are temperature sensitive, as shown in Figure 17. Pulse techniques must be used that maintain the junction temperatures as close to the ambient temperature as possible.

operating characteristics, $V_{CC\pm}$ = ±15 V, T_A = 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS				MIN	TYP	MAX	UNIT
SR	Slew rate at unity gain	V_I = 10 V,	R_L = 2 kΩ,	C_L = 100 pF,	See Figure 1	8*	13		V/μs
		V_I = 10 V, T_A = − 55°C to 125°C,	R_L = 2 kΩ, See Figure 1	C_L = 100 pF,		5*			
t_r	Rise time	V_I = 20 mV,	R_L = 2 kΩ,	C_L = 100 pF,	See Figure 1		0.05		μs
	Overshoot factor						20		%
V_n	Equivalent input noise voltage	R_S = 20 Ω	f = 1 kHz				18		nV/√Hz
			f = 10 Hz to 10 kHz				4		μV
I_n	Equivalent input noise current	R_S = 20 Ω,	f = 1 kHz				0.01		pA/√Hz
THD	Total harmonic distortion	$V_I$rms = 6 V, f = 1 kHz	A_{VD} = 1,	R_S ≤ 1 kΩ,	R_L ≥ 2 kΩ,		0.003		%

*On products compliant to MIL-PRF-38535, this parameter is not production tested.

operating characteristics, $V_{CC\pm}$ = ±15 V, T_A = 25°C

PARAMETER		TEST CONDITIONS				MIN	TYP	MAX	UNIT
SR	Slew rate at unity gain	V_I = 10 V,	R_L = 2 kΩ,	C_L = 100 pF,	See Figure 1	8	13		V/μs
t_r	Rise time	V_I = 20 mV,	R_L = 2 kΩ,	C_L = 100 pF,	See Figure 1		0.05		μs
	Overshoot factor						20		%
V_n	Equivalent input noise voltage	R_S = 20 Ω	f = 1 kHz				18		nV/√Hz
			f = 10 Hz to 10 kHz				4		μV
I_n	Equivalent input noise current	R_S = 20 Ω,	f = 1 kHz				0.01		pA/√Hz
THD	Total harmonic distortion	$V_I$rms = 6 V, f = 1 kHz	A_{VD} = 1,	R_S ≤ 1 kΩ,	R_L ≥ 2 kΩ,		0.003		%

PARAMETER MEASUREMENT INFORMATION

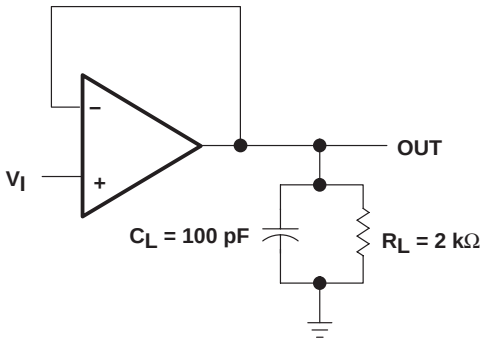


Figure 1

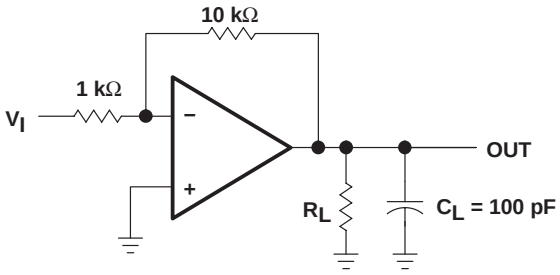


Figure 2

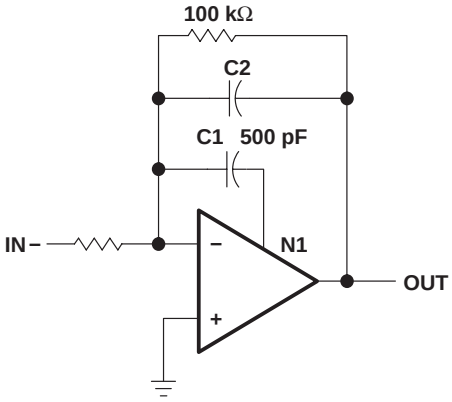


Figure 3

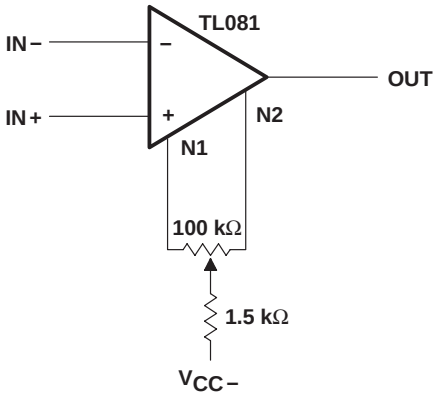


Figure 4

TYPICAL CHARACTERISTICS

Table of Graphs

			FIGURE
V_{OM}	Maximum peak output voltage	vs Frequency vs Free-air temperature vs Load resistance vs Supply voltage	5, 6, 7 8 9 10
A_{VD}	Large-signal differential voltage amplification	vs Free-air temperature vs Frequency	11 12
	Differential voltage amplification	vs Frequency with feed-forward compensation	13
P_D	Total power dissipation	vs Free-air temperature	14
I_{CC}	Supply current	vs Free-air temperature vs Supply voltage	15 16
I_{IB}	Input bias current	vs Free-air temperature	17
	Large-signal pulse response	vs Time	18
V_O	Output voltage	vs Elapsed time	19
CMRR	Common-mode rejection ratio	vs Free-air temperature	20
V_n	Equivalent input noise voltage	vs Frequency	21
THD	Total harmonic distortion	vs Frequency	22

MAXIMUM PEAK OUTPUT VOLTAGE vs FREQUENCY

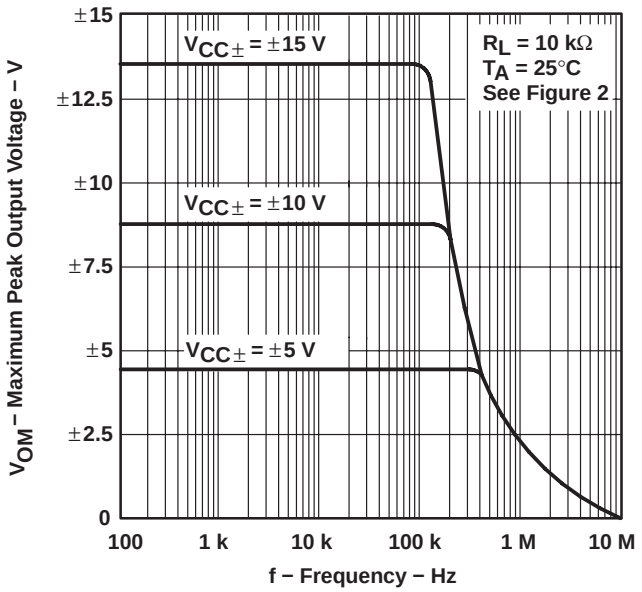


Figure 5

MAXIMUM PEAK OUTPUT VOLTAGE vs FREQUENCY

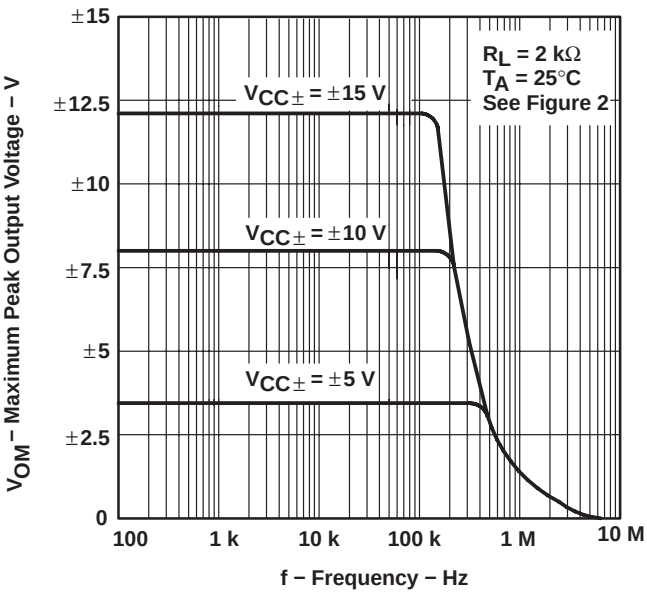


Figure 6

TYPICAL CHARACTERISTICS†

MAXIMUM PEAK OUTPUT VOLTAGE vs FREQUENCY

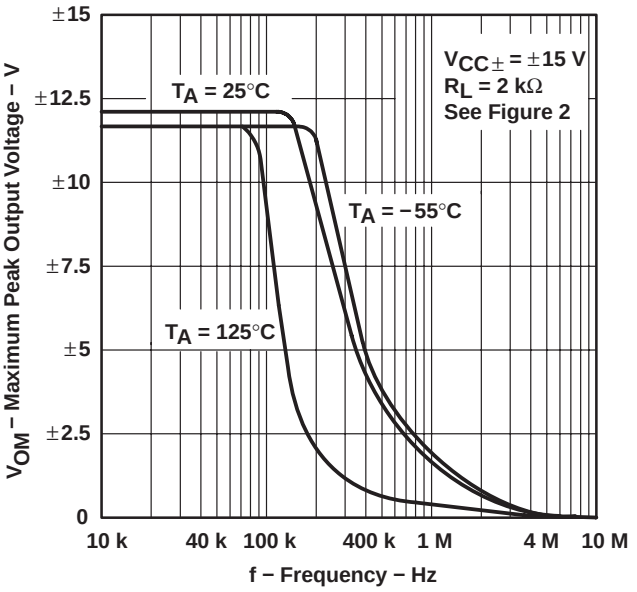


Figure 7

MAXIMUM PEAK OUTPUT VOLTAGE vs FREE-AIR TEMPERATURE

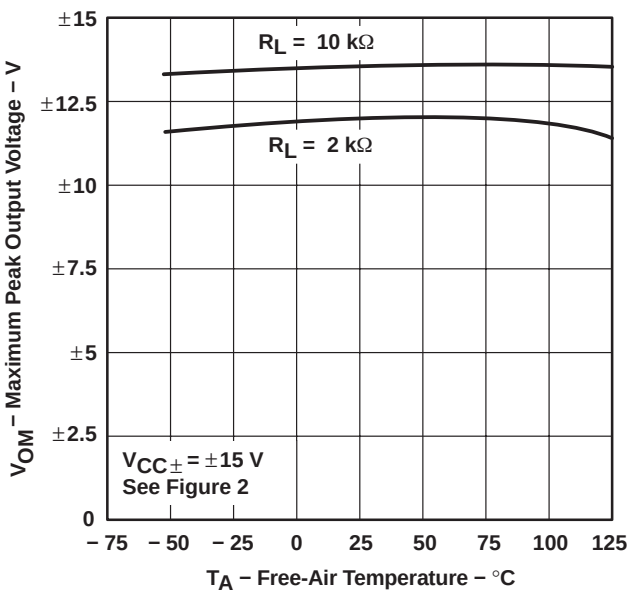


Figure 8

MAXIMUM PEAK OUTPUT VOLTAGE vs LOAD RESISTANCE

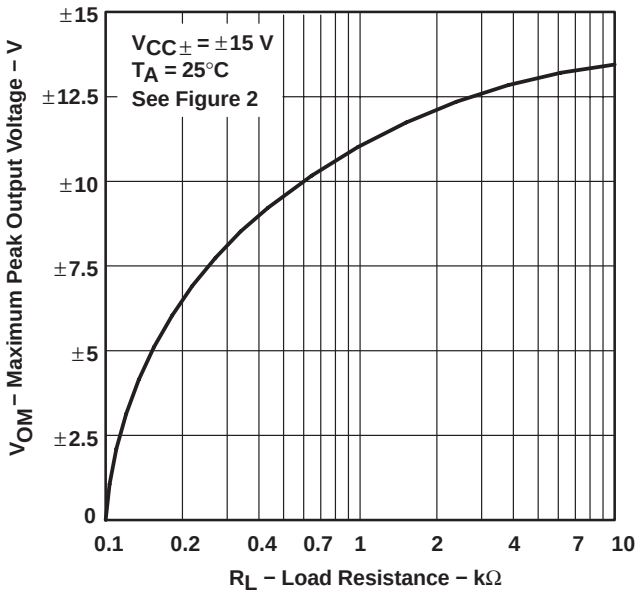


Figure 9

MAXIMUM PEAK OUTPUT VOLTAGE vs SUPPLY VOLTAGE

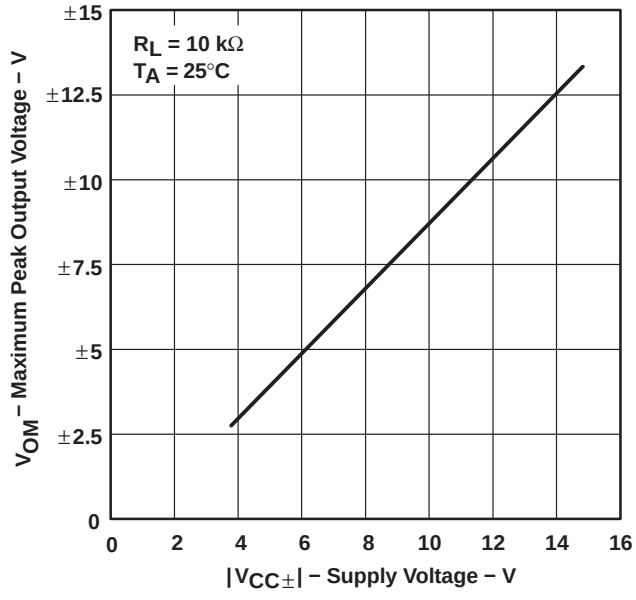


Figure 10

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS†

LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION vs FREE-AIR TEMPERATURE

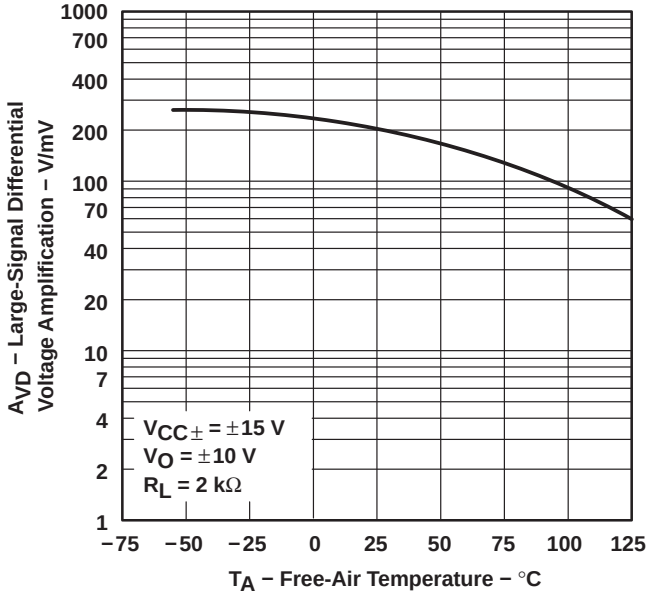


Figure 11

LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION vs FREQUENCY

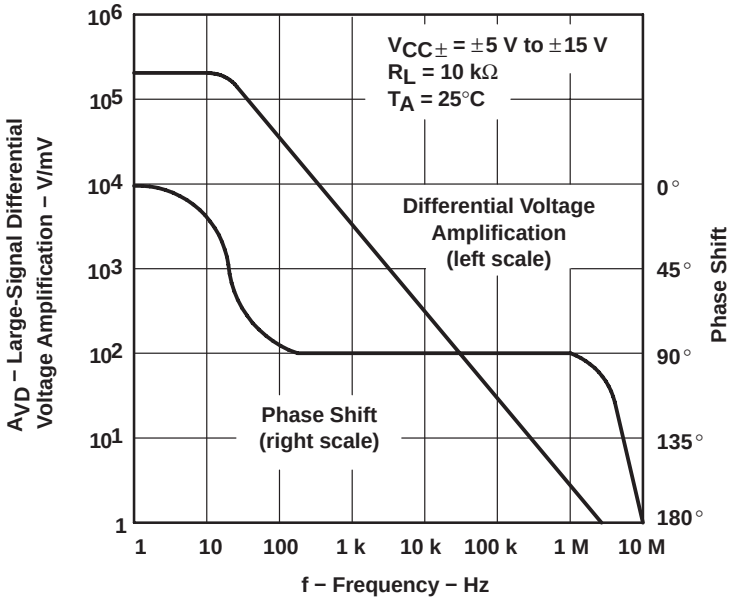


Figure 12

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS†

DIFFERENTIAL VOLTAGE AMPLIFICATION vs FREQUENCY WITH FEED-FORWARD COMPENSATION

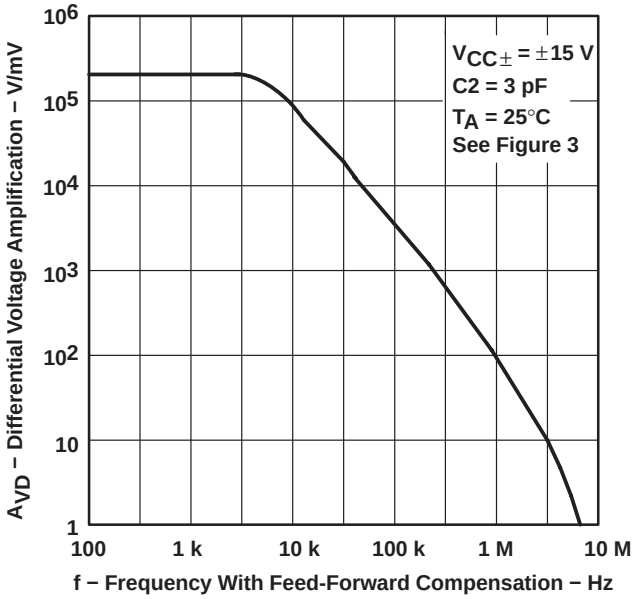


Figure 13

TOTAL POWER DISSIPATION vs FREE-AIR TEMPERATURE

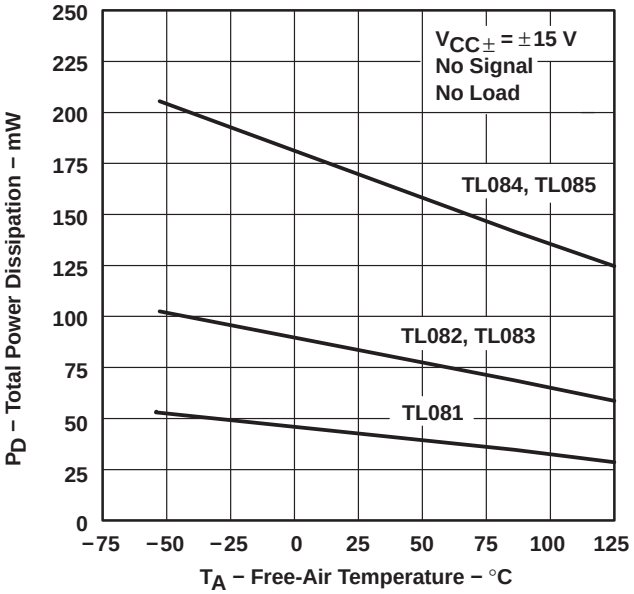


Figure 14

SUPPLY CURRENT PER AMPLIFIER vs FREE-AIR TEMPERATURE

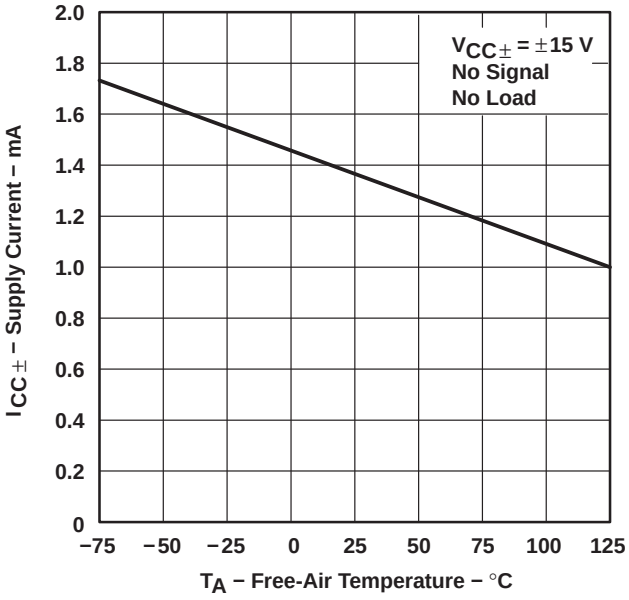


Figure 15

SUPPLY CURRENT vs SUPPLY VOLTAGE

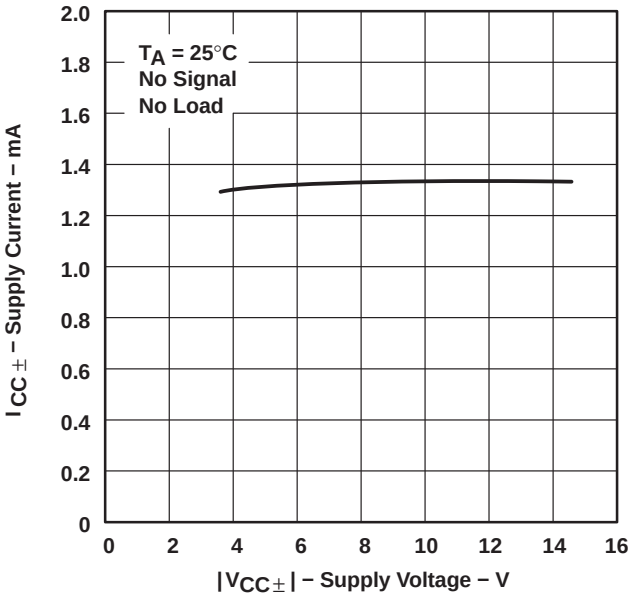


Figure 16

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS†

INPUT BIAS CURRENT vs FREE-AIR TEMPERATURE

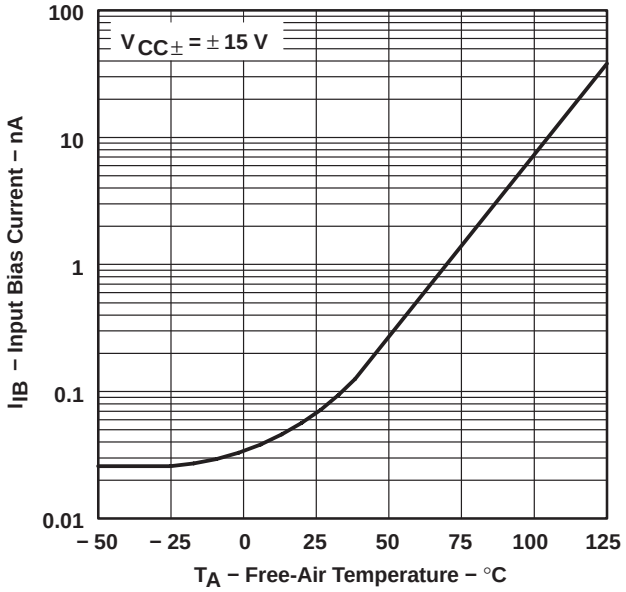


Figure 17

VOLTAGE-FOLLOWER LARGE-SIGNAL PULSE RESPONSE

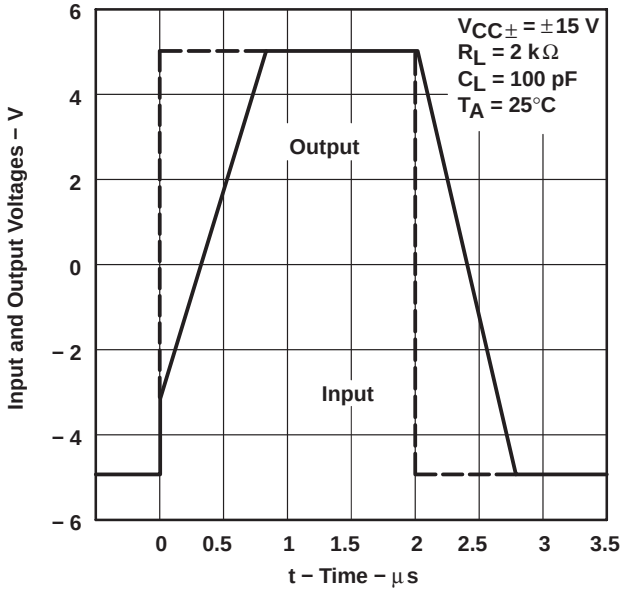


Figure 18

OUTPUT VOLTAGE vs ELAPSED TIME

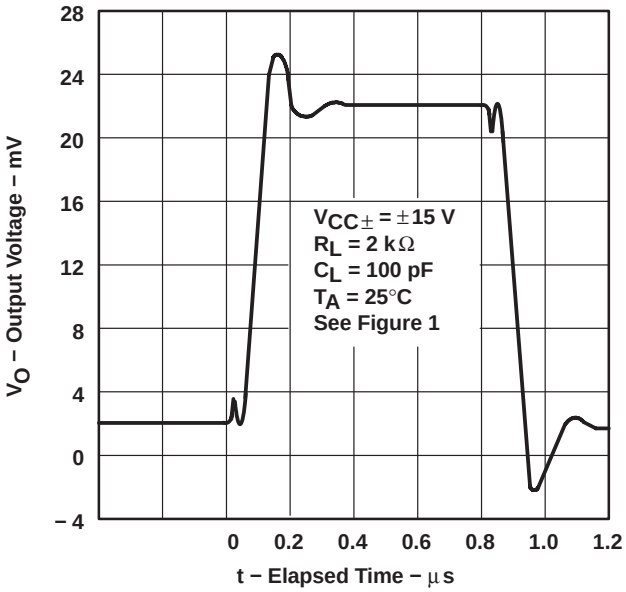


Figure 19

COMMON-MODE REJECTION RATIO vs FREE-AIR TEMPERATURE

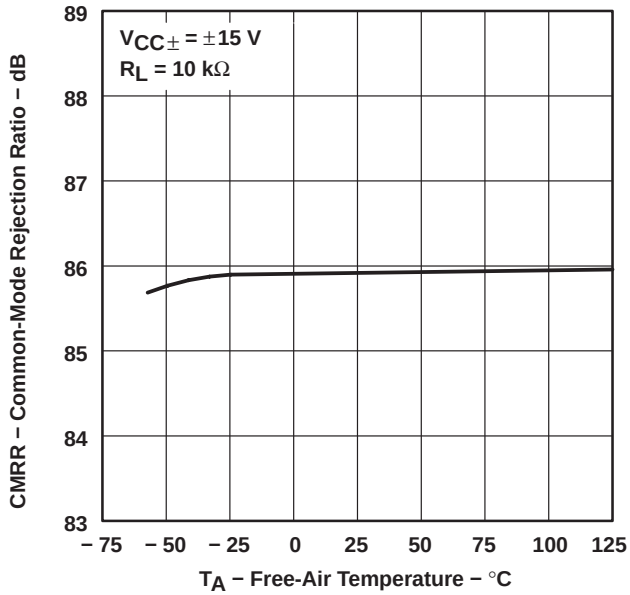


Figure 20

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

TYPICAL CHARACTERISTICS†

EQUIVALENT INPUT NOISE VOLTAGE vs FREQUENCY

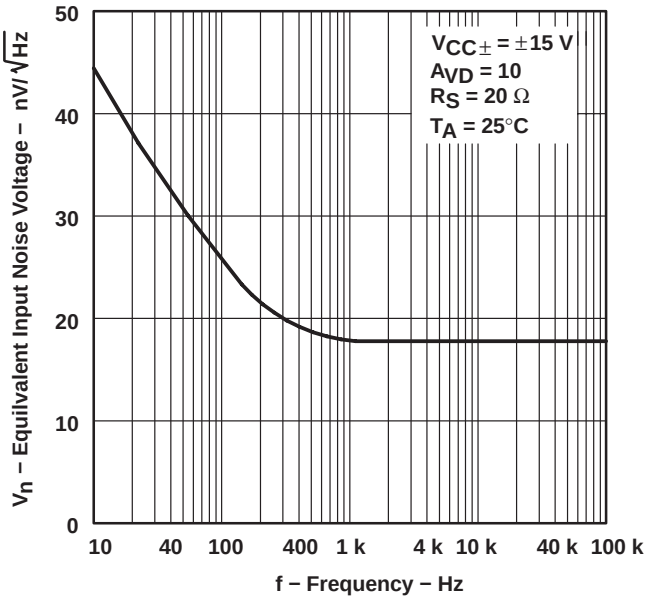


Figure 21

TOTAL HARMONIC DISTORTION vs FREQUENCY

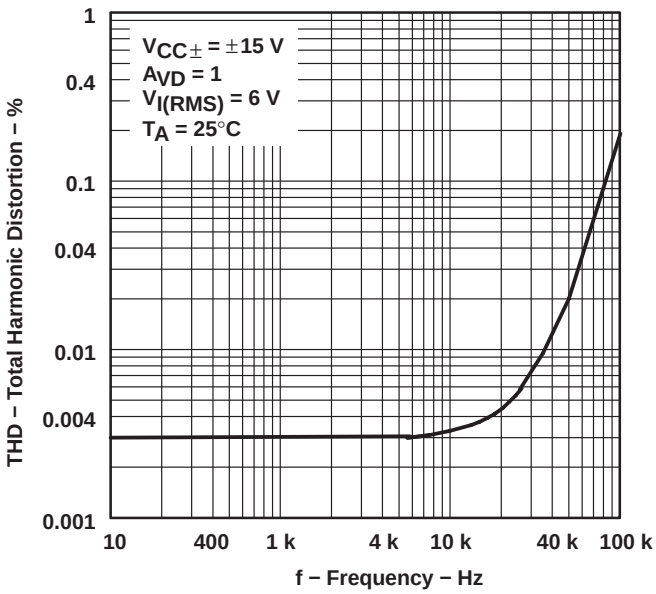


Figure 22

† Data at high and low temperatures are applicable only within the rated operating free-air temperature ranges of the various devices.

APPLICATION INFORMATION

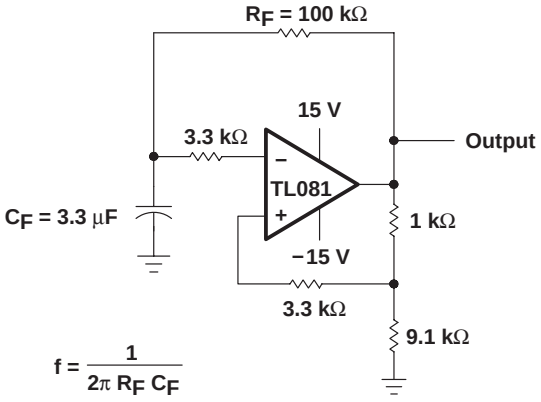


Figure 23

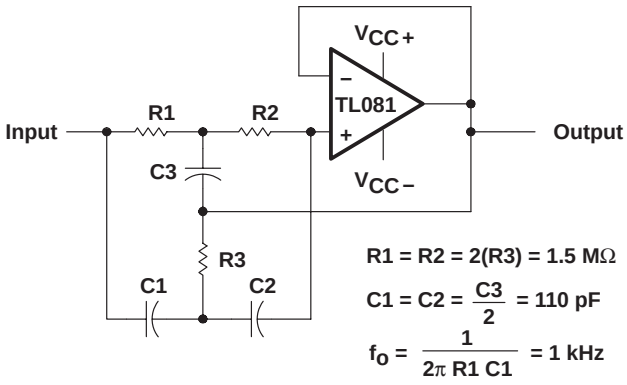


Figure 24

APPLICATION INFORMATION

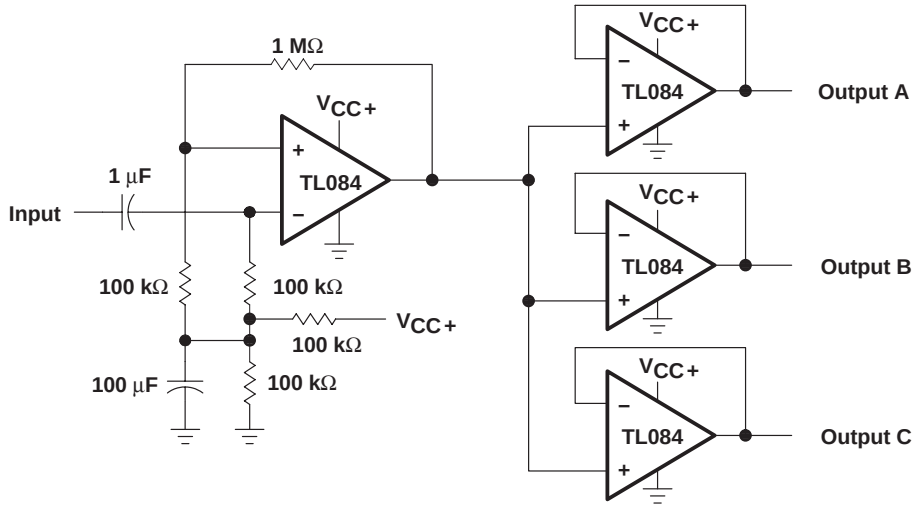
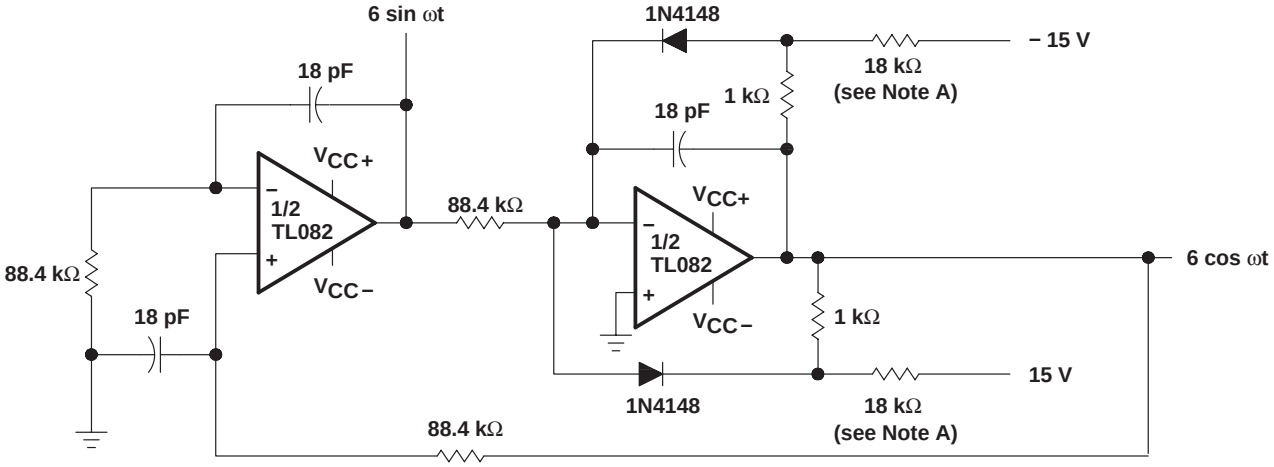


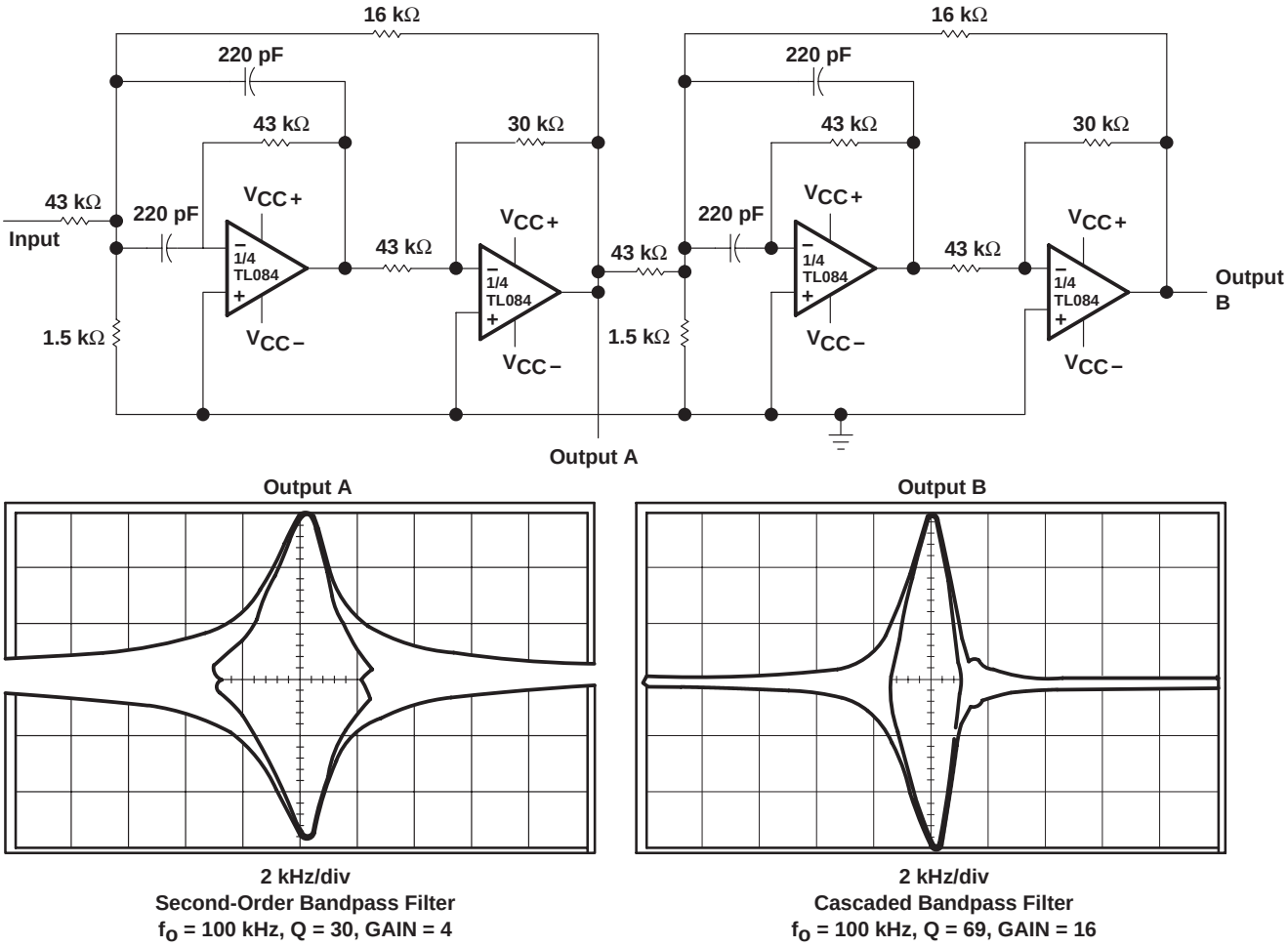
Figure 25. Audio-Distribution Amplifier



NOTE A: These resistor values may be adjusted for a symmetrical output.

Figure 26. 100-KHz Quadrature Oscillator

APPLICATION INFORMATION



Output A

2 kHz/div
Second-Order Bandpass Filter
f_O = 100 kHz, Q = 30, GAIN = 4

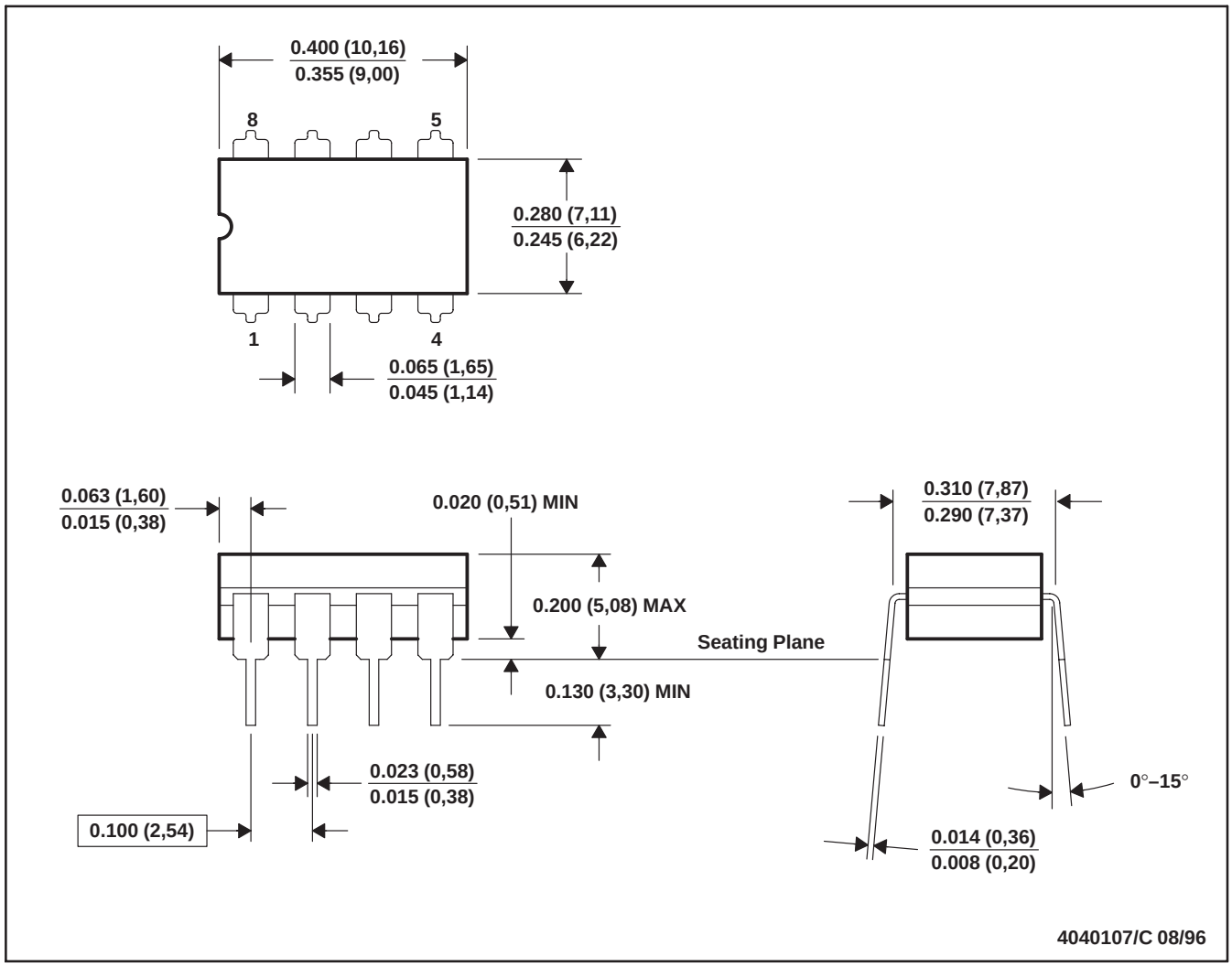
Output B

2 kHz/div
Cascaded Bandpass Filter
f_O = 100 kHz, Q = 69, GAIN = 16

Figure 27. Positive-Feedback Bandpass Filter

MCER001A – JANUARY 1995 – REVISED JANUARY 1997

JG (R-GDIP-T8) **CERAMIC DUAL-IN-LINE**

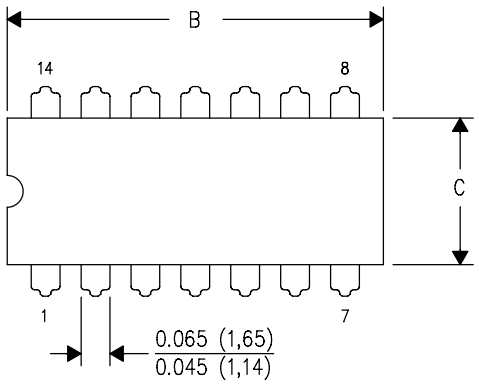


NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification.
E. Falls within MIL STD 1835 GDIP1-T8

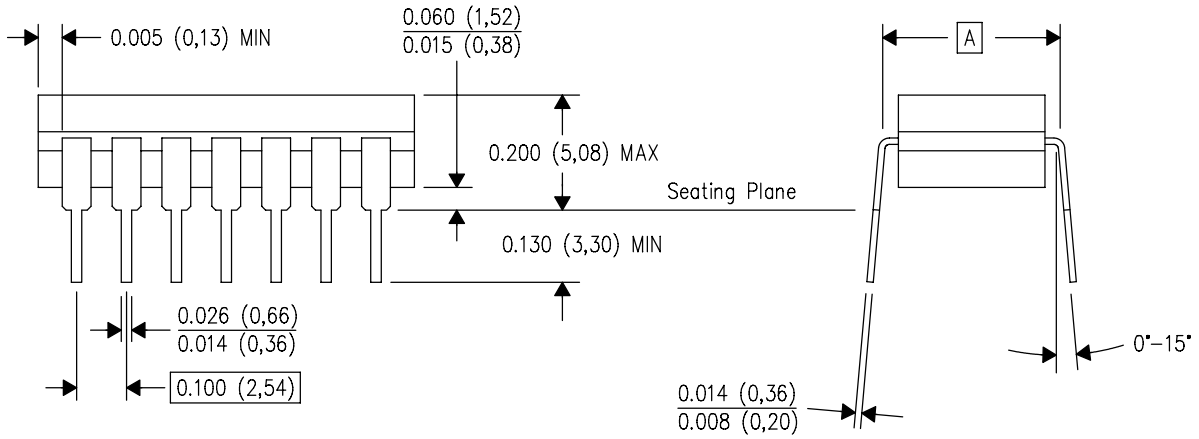
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

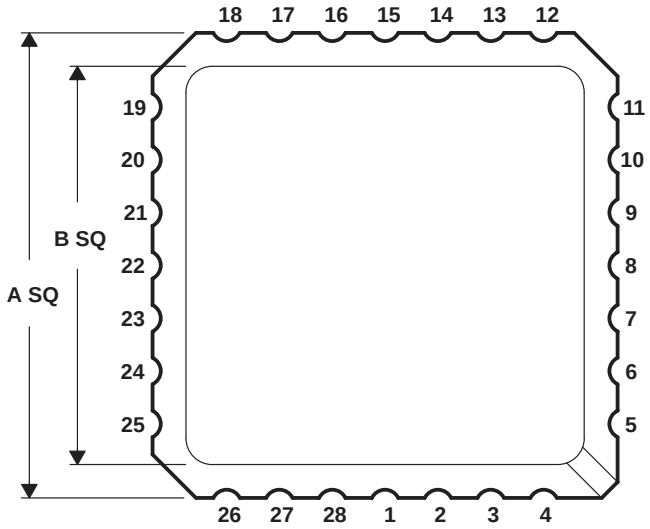


4040083/F 03/03

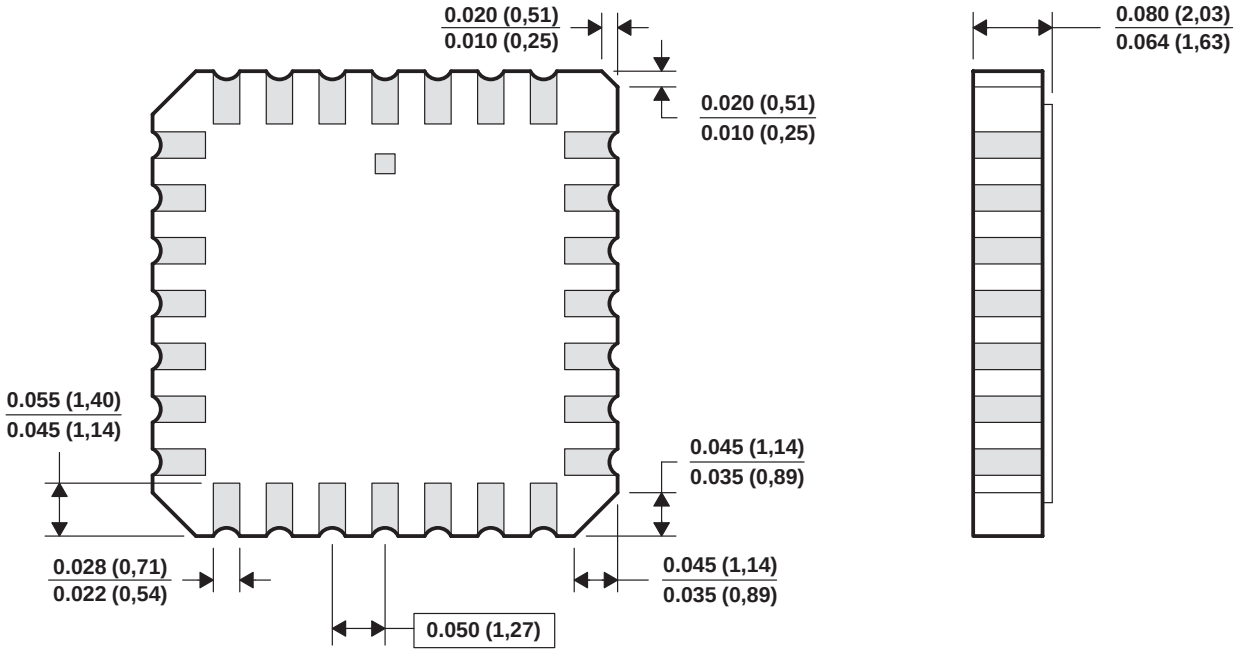
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

FK (S-CQCC-N)** **LEADLESS CERAMIC CHIP CARRIER**

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.739 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

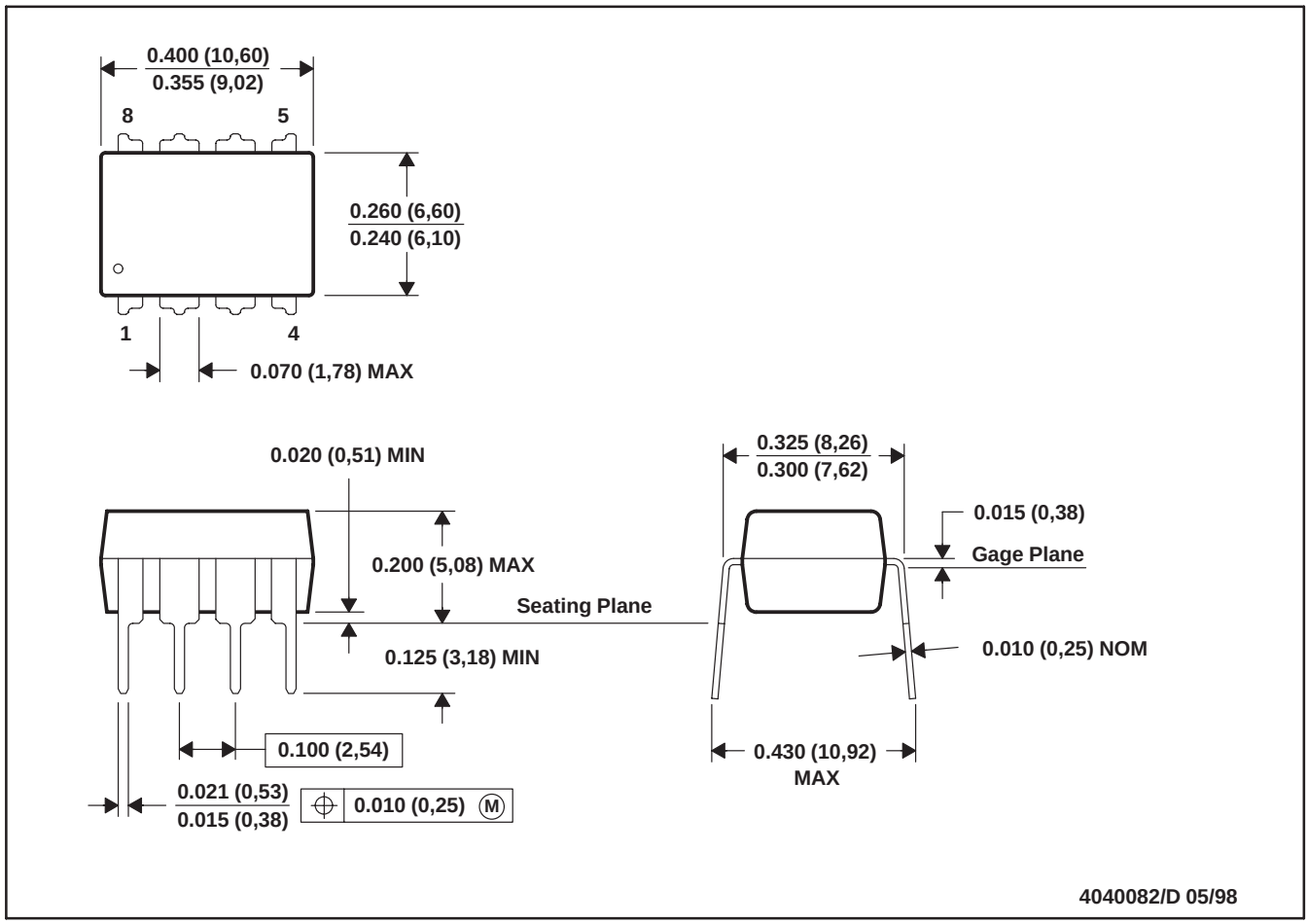


4040140/D 10/96

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. The terminals are gold plated.
E. Falls within JEDEC MS-004

MPDI001A – JANUARY 1995 – REVISED JUNE 1999

P (R-PDIP-T8) **PLASTIC DUAL-IN-LINE**



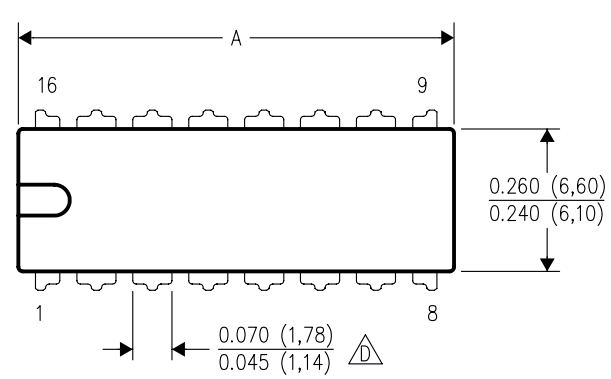
NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm

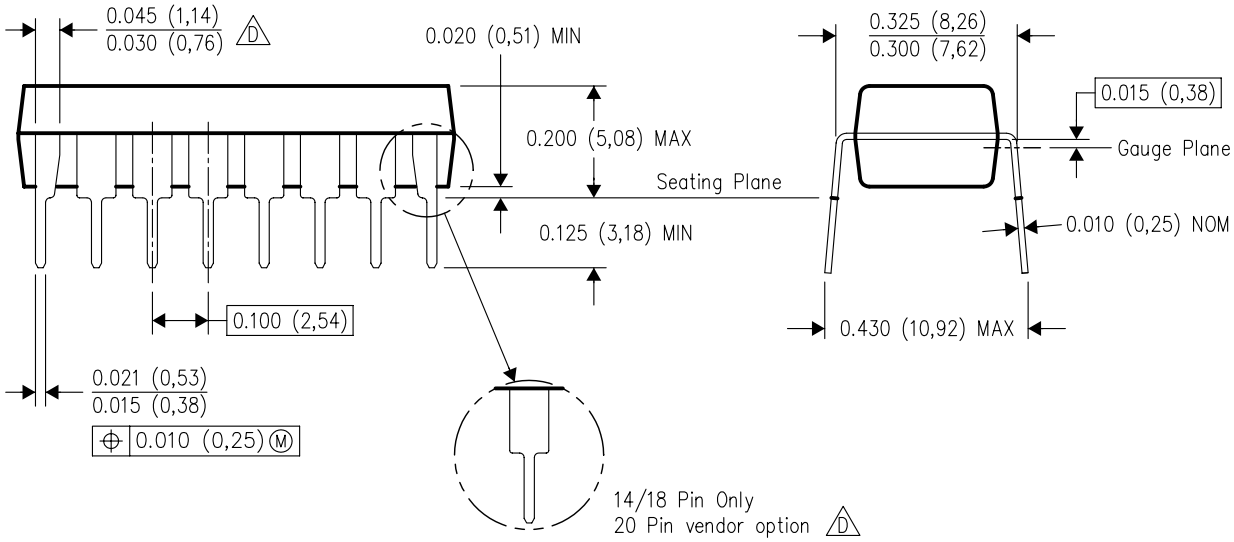
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



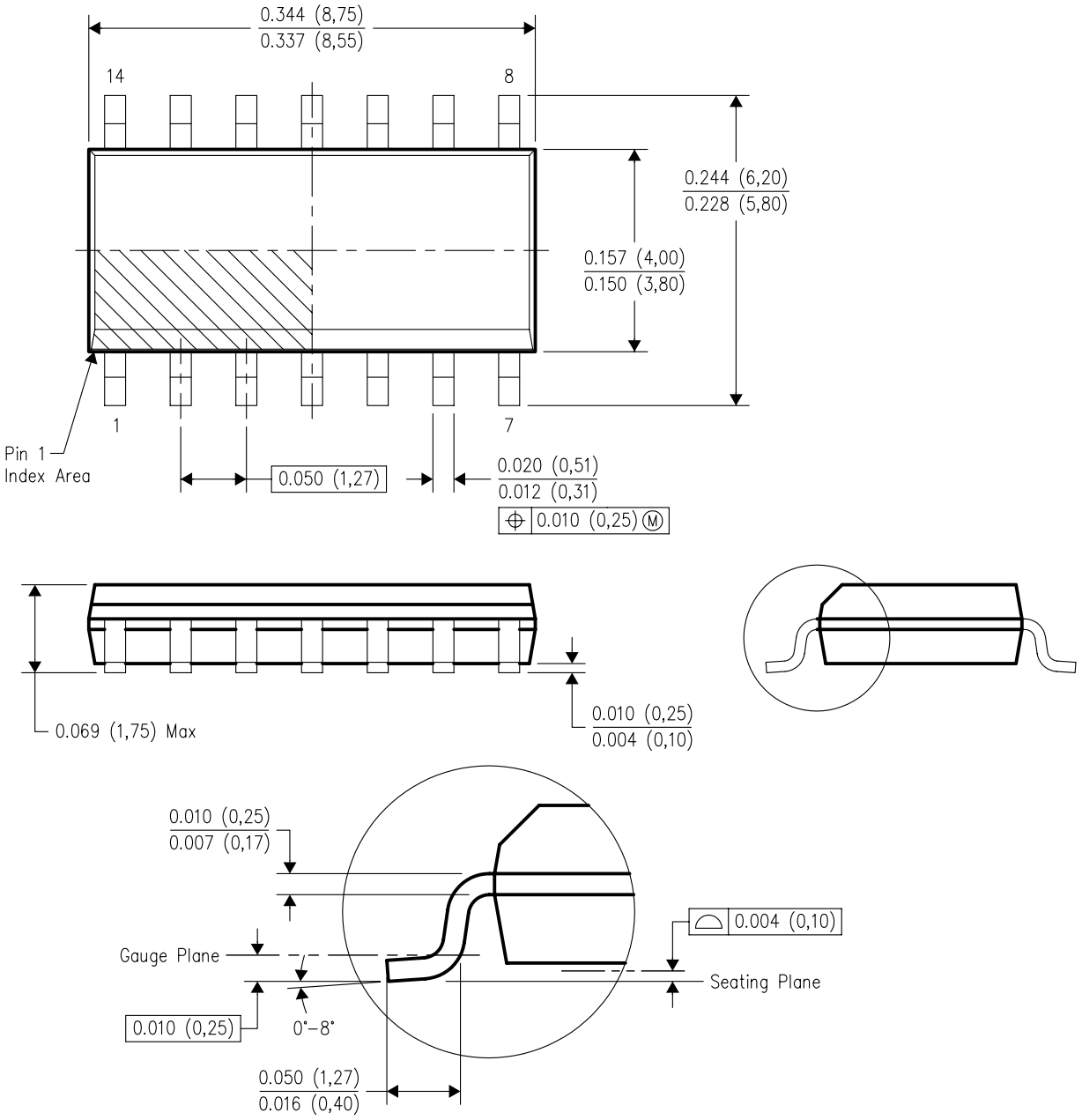
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

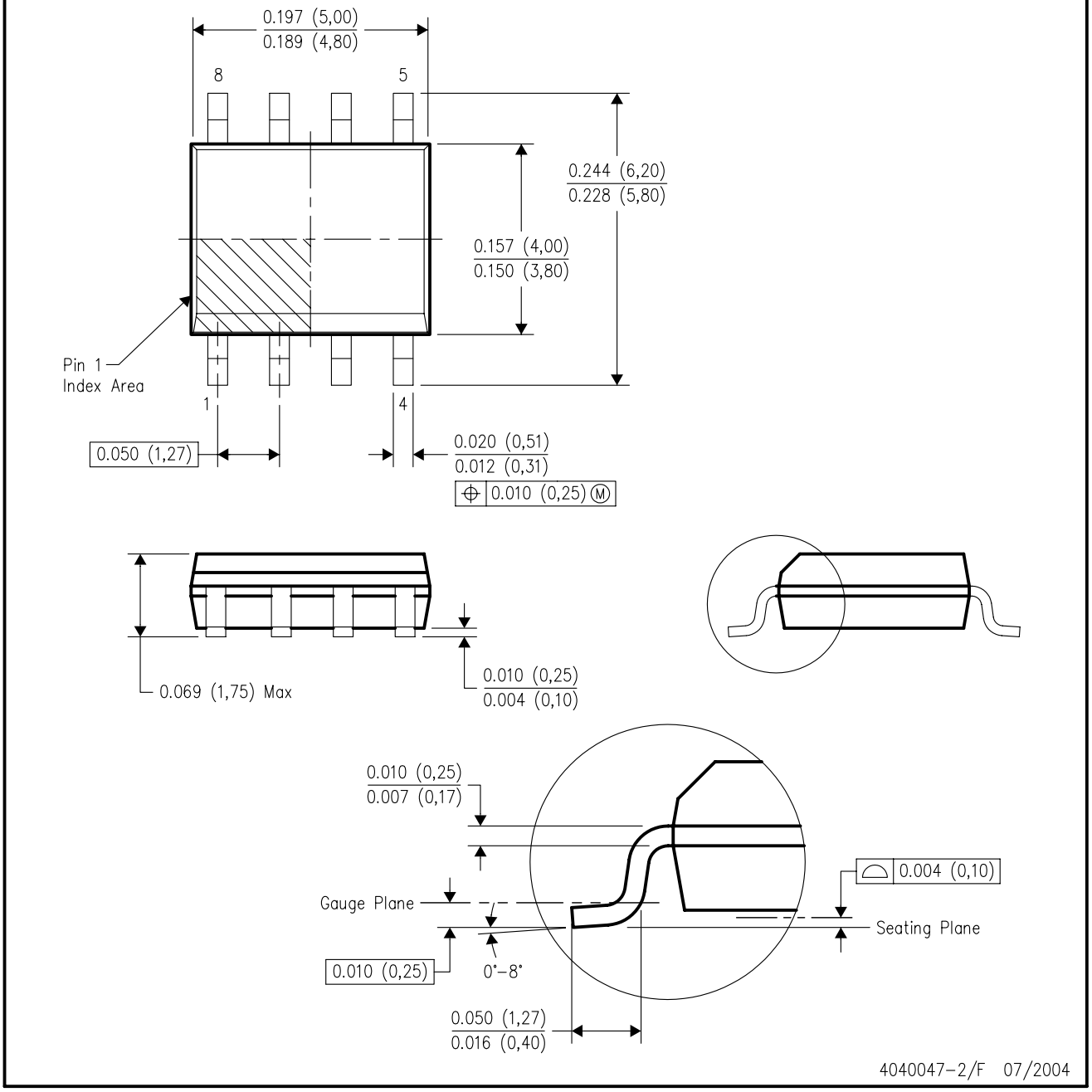
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G14) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–012 variation AB.

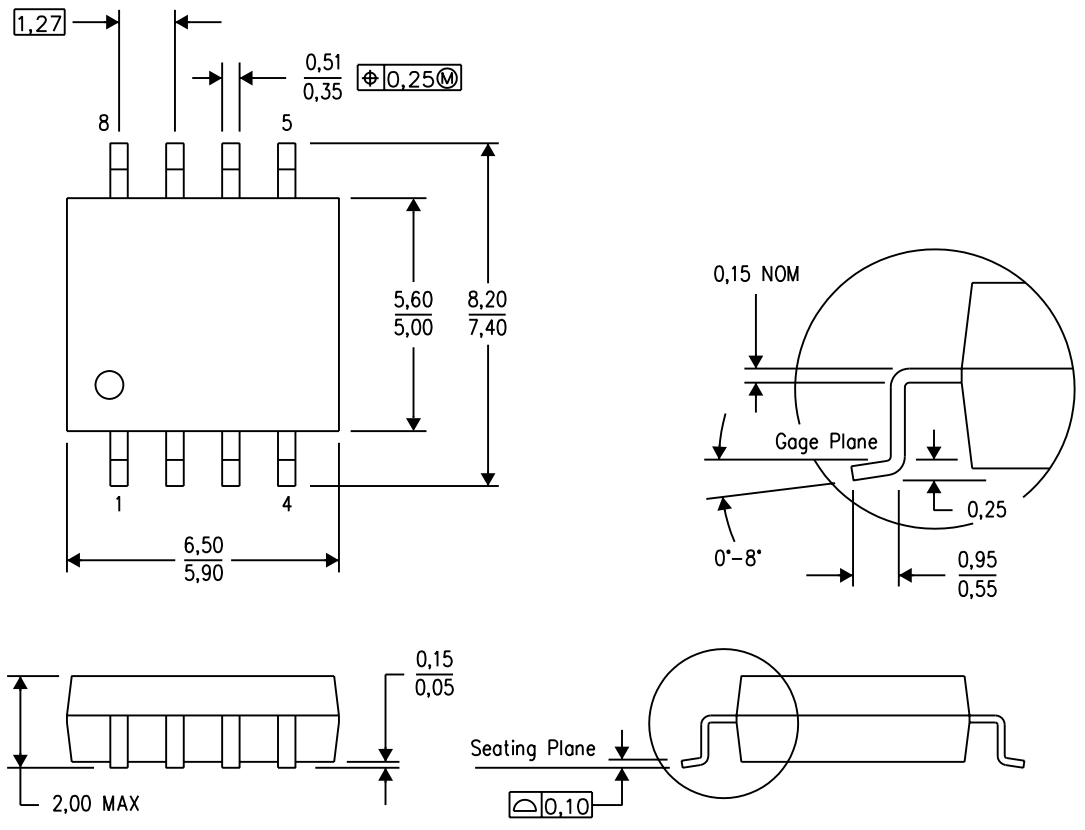
D (R–PDSO–G8) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–012 variation AA.

MECHANICAL DATA

PS (R-PDSO-G8) **PLASTIC SMALL-OUTLINE PACKAGE**



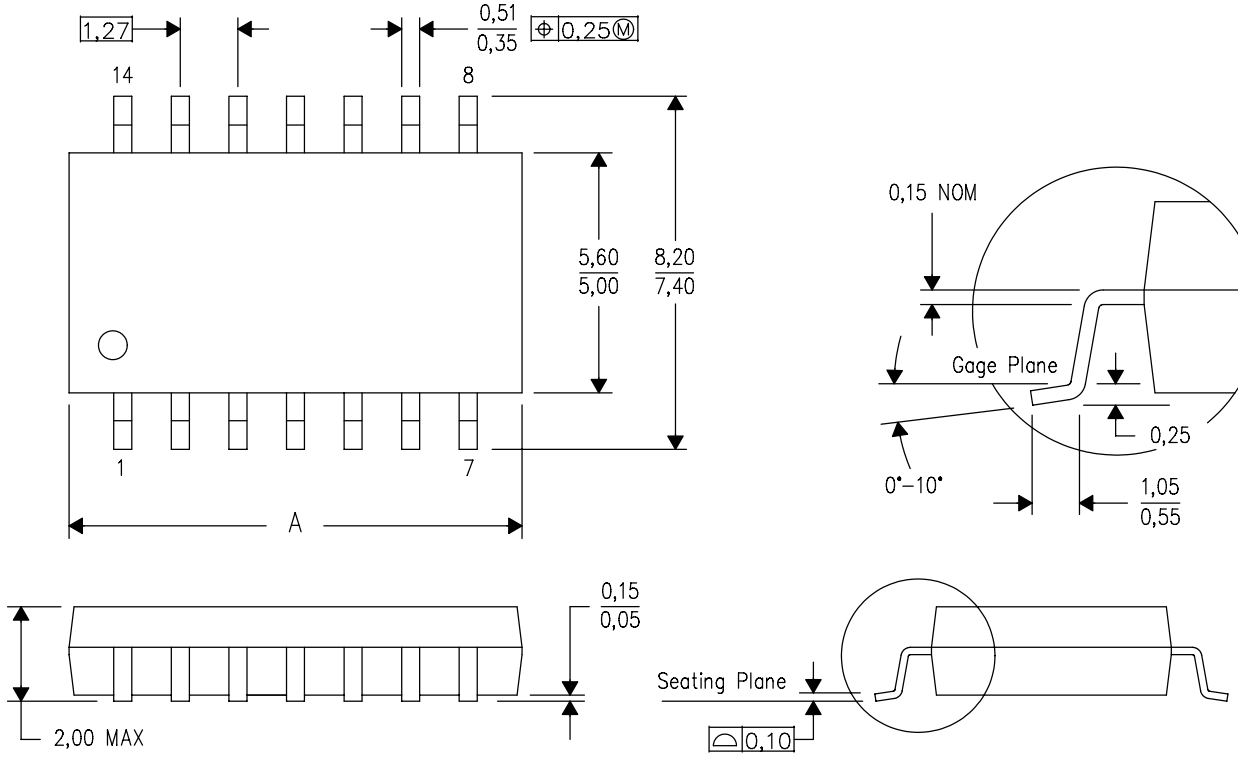
4040063/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



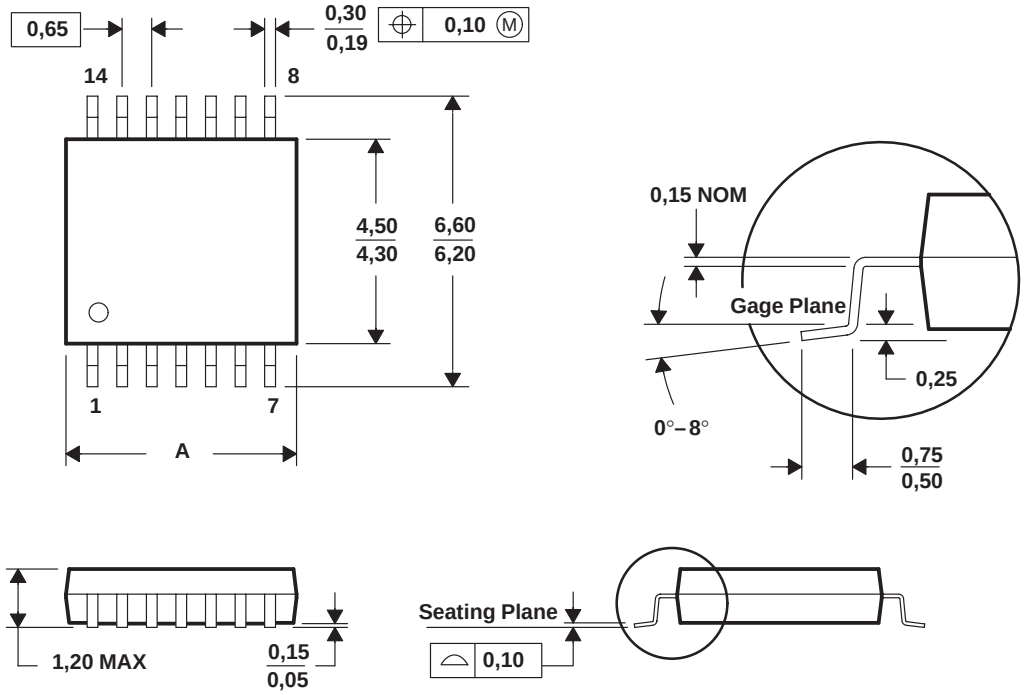
DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PW (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14 PINS SHOWN



DIM \ PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

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